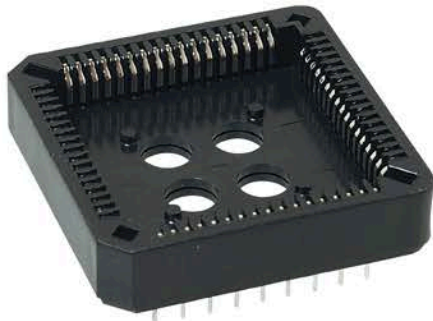


PLCC Sockets Through Board



Electrical Performance:

Contact interface resistance:

Initial: 6.5 Milliohms average

Final: 15.0 Milliohms average max. after testing

Insulation resistance: 10000 Megaohms min.

Dielectric strength: 1000VAC continuous for 1 minute

Capacitance: less than 1.0pf at 1000kHz

Operating and storage temperature: -40°C to +105°C

Material:

Insulator: A: 40% glasses filled in P.P.S. UL-94V-0 brown

Insulator: B: 30% glasses filled in P.B.T. UL-94V-0 black

Insulator: C: 45% glasses filled in NYLON9T UL-94V-0 black

Contact: phosphor bronze, 0.25mm thickness

Plated: tin plated 160µ" over nickel (lead free)

Plated: matte tin plated 150µ" over nickel (lead free)

Durability: per MIL-STD-1344, method 2016, 25 cycles

Vibration: per MIL-STD-810c, method 514.2 10-200,000Hz 5Gs

Shock: per MIL-STD-810C, method 516.2, 35Gs

Acceleration: per MIL-STD-810C, method 5.13.2, 15Gs

Contact force: 170g/per pin

Features:

- Applications include all electronic PC boards requiring the conversion of a 0.05" pitch chip carrier to a 0.1" x 0.1" grid through board application
- Accepts moulded plastic chip carriers conforming to JEDEC specification MO-047 for square and MO-052 for rectangle configuration
- Visual and mechanical polarisation for PLCC insertion
- Closed button for excellent protection solder wicking into contact area
- Moulded-in stand-offs allow easy removal to flux residue
- Extraction tool slots
- Open top design for cooler running chip carrier
- Automatic insertion machine compatible

No. of Pins & Type	Insulator	Dimensions			
		A±0.5	B±0.3	C±0.1	D±0.2
28 M type	PBT or PPS	18.05	18.05	7.62	7.62
32 M type	PBT or PPS	18.05	20.60	7.62	10.16
44 M type	PBT or PPS	23.50	23.50	12.70	12.70
52 M type	PBT or PPS	25.88	25.88	15.24	15.24
68 M type	PPS or NY	31.05	31.05	20.30	20.30
84 M type	PPS or NY	36.05	36.05	25.40	25.40

Environmental Performance:

Thermal shock: per MIL-STD-1344, method 1003, condition A, cycled from +55°C to +80°C, no discontinuity or physical damage.

Temperature/humidity: per MIL-STD-1344, method 1002, 85°C/85% relative humidity.

